



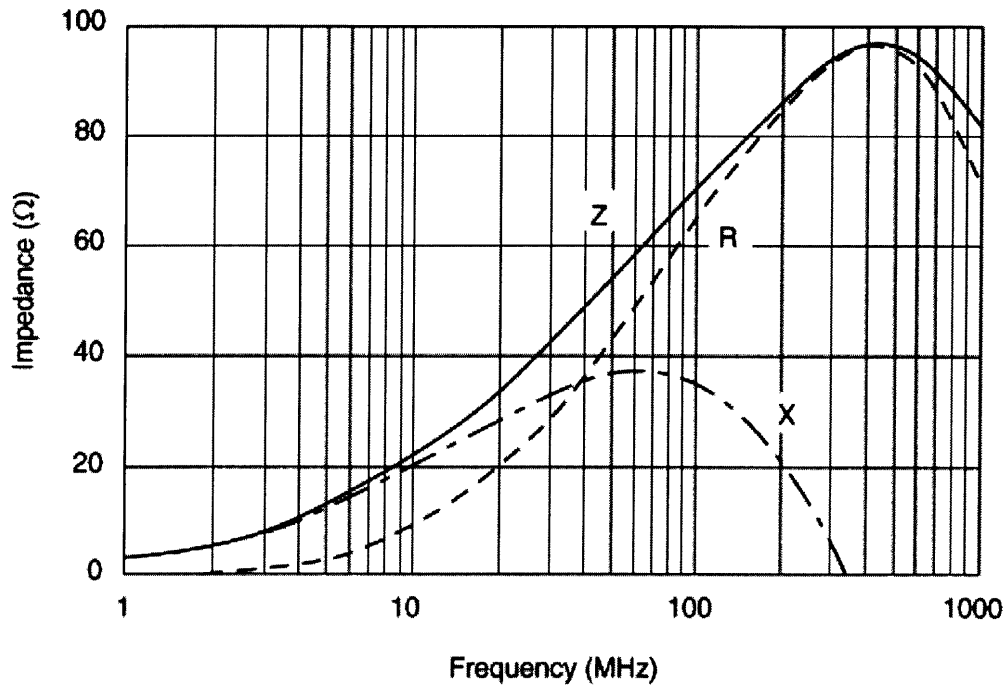
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Noise Suppression Products/EMIFIL EMIFIL(SMD) Inductor Type



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Noise Suppression Products/EMIFIL > EMIFIL(SMD) > Inductor Type

Specification

Details

Part Number	BLM41P800S
Impedance (at 100MHz)	80ohm (Typ.)
Rated Current	1000mA
DC Resistance(max.)	0.10ohm
Min. of Operating Temp.	-55°C
Max. of Operating Temp.	125°C
Length	4.5mm
Width	1.6mm
Thickness	1.6mm
Number of Circuit	1
EIA	1806
Maximum Signal Frequency	
Weight	0.06g (Typ.)

-  Appearance
-  Dimension
-  Z-f Characteristics(Typ.)
-  Z-f of Main Items
-  Features
-  Equivalent Circuit
-  Mounting
-  Packaging
-  Notice (storage and operating condition)
-  Caution (rating)
-  Caution (soldering and mounting)

Minimum Quantity

180mm Paper Tape	
180mm Plastic Tape	2500
330mm Paper Tape	
330mm Plastic Tape	8000
Bulk Case	
Bulk(Bag)	1000
Flat Pack	
335Reel	
Magazine	
Box	

Product specifications in this catalog are as of Fed. '00, and are subject to change or obsolescence without notice.

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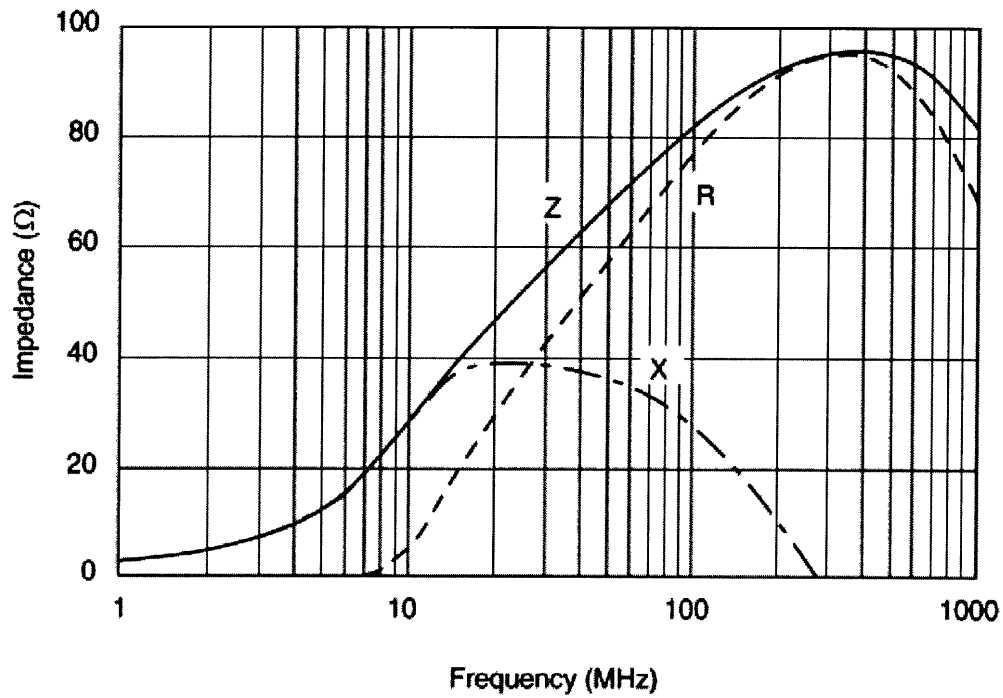
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Noise Suppression Products/EMIFIL EMIFIL(SMD) Inductor Type



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Home >Product Information >Search Engine >Catalog: **BLM41P600S**

Noise Suppression Products/EMIFIL > EMIFIL(SMD) > Inductor Type

Specification

Part Number	BLM41P600S
Impedance (at 100MHz)	60ohm (Typ.)
Rated Current	6000mA
DC Resistance(max.)	0.01ohm
Min. of Operating Temp.	-55°C
Max. of Operating Temp.	125°C
Length	4.5mm
Width	1.6mm
Thickness	1.6mm
Number of Circuit	1
EIA	1806
Maximum Signal Frequency	
Weight	0.06g (Typ.)

Details

-  [Appearance](#)
-  [Dimension](#)
-  [Z-f Characteristics\(Typ.\)](#)
-  [Z-f of Main Items](#)
-  [Features](#)
-  [Equivalent Circuit](#)
-  [Mounting](#)
-  [Packaging](#)
-  [Notice \(storage and operating condition\)](#)
-  [Caution \(rating\)](#)
-  [Caution \(soldering and mounting\)](#)

Minimum Quantity

180mm Paper Tape	
180mm Plastic Tape	2500
330mm Paper Tape	
330mm Plastic Tape	8000



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The Murata logo, featuring the word "murata" in a stylized, lowercase font with a distinctive wave-like underline.



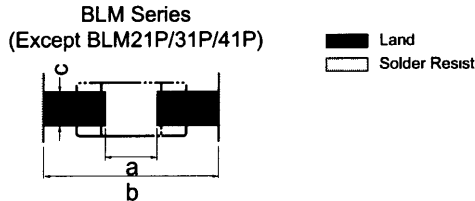
The chip ferrite bead BLM series comprises ferrite bead inductors in the shape of a chip. This inductor generates a high impedance which at high frequencies mainly consists of a resistance element. The BLM series is effective in circuits without stable ground lines because the BLM series does not need a connection to ground. The BLM series comprises the R series (for Digital Interface), the A series (general), the B series (for high freq. signal), and the P series (high current).

The nickel barrier structure of the external electrodes provides excellent solder heat resistance. Both flow and reflow soldering methods can be employed.

The BLM-P series can be used in high current circuits due to its low DC resistance. It can match power lines to a maximum of 6A DC (BLM41P).

1. Standard Land Pattern Dimensions

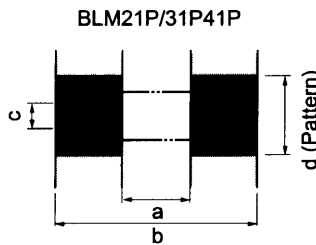
The capacitor type chip EMI suppression filters (NFM/NFA series) suppress noise by conducting the high-frequency noise element to ground. Therefore, to obtain maximum performance from these filters, the ground pattern should be made as large as possible during the PCB design stage. As shown below, one side of the PCB is used for chip mounting, and the other is used for grounding. Small diameter feedthrough holes are then used to connect the grounds on each side of the PCB. This reduces the high-frequency impedance of the grounding and maximizes the filter's performance.



Type	Dimension (mm)				
	L	W	a	b	c
*BLM10 (Reflow)	1.0	0.5	0.4	1.2-1.4	0.5
BLM11 (Flow)	1.6	0.8	0.7	2.2-2.6	0.7
BLM11 (Reflow)	1.6	0.8	0.7	1.8-2.0	0.7
BLM21	2.0	1.25	1.2	3.0-4.0	1.0
BLM31	3.2	1.6	2.0	4.2-5.2	1.2
BLM41	4.5	1.6	3.0	5.5-6.5	1.2

*BLM10 is specially adapted for reflow soldering .

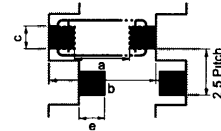
Do not apply narrower pattern than listed above to BLM__P. Narrow pattern can cause excessive heat or open circuit.



Type	Rated Current (A)	Size(mm)			Land pad thickness and Dimension d		
		a	b	c	18µm	35µm	70µm
BLM21P331SG	1.5	1.2	3.0-4.0	1.0	1.0	1.0	1.00
BLM21P221SG	2				1.2	1.0	1.00
BLM21P300S/ BLM21P600SG	3				2.4	1.2	1.00
BLM21P220SG	6	2.0	4.5-5.2	1.2	6.4	3.3	1.65
BLM31P330SG	6				2.4	1.2	1.20
BLM31P500S/ BLM31P121SG	3				2.4	1.2	1.20
BLM31P391SG	2	3.0	5.5-6.5	1.2	1.2	1.2	1.20
BLM31P601SG	1.5				2.4	1.2	1.20
BLM41P800S	1				6.4	3.3	1.65
BLM41P102SG	1.5	3.0	5.5-6.5	1.2	1.2	1.2	1.20
BLM41P471SG	2				2.4	1.2	1.20
BLM41P750S/ BLM41P181SG	3				6.4	3.3	1.65
BLM41P600S	6						

• Please contact us if using thinner land pad than 18µm.

Flow mounting in high density for BLM31/41



Type	Dimension(mm)				
	a	b	c	d	e
BLM31	2.0	4.2-5.2	1.2	1.3	1.35
BLM41	3.0	5.5-6.5	1.2	1.8	1.5

2. Solder Paste Printing and Adhesive Application

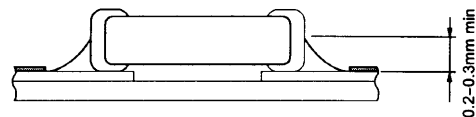
When reflow soldering the chip EMI suppression filter, the printing must be conducted in accordance with the following cream solder printing conditions. If too much solder is applied, the chip will prone to be damaged by mechanical and thermal stress from the PCB and may crack. In contrast, if too little solder is applied, there is the potential that the termination strength will be insufficient, creating the potential for detachment. Standard land dimensions should be used for resist and copper foil patterns.

When flow soldering the EMI suppression filter, apply the adhesive in accordance with the following conditions. If too much adhesive is applied, then it may overflow into the land or termination areas and yield poor solderability. In contrast, if insufficient adhesive is applied, or if the adhesive is not sufficiently hardened, then the chip may become detached during flow soldering process.

Solder Paste Printing

BLM Series

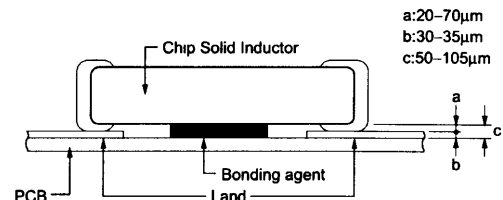
- Ensure that solder is applied smoothly to a minimum height of 0.2mm to 0.3mm at the end surface of the part.
- Coat the solder paste a thickness of 100µm to 200µm.



Adhesive Application

BLM Series

- Coating amount is illustrated in the following diagram.



3. Standard Soldering Conditions

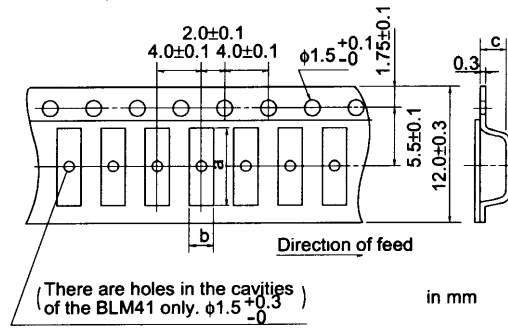
SOLDERING METHODS

Use flow and reflow soldering methods only.
Use standard soldering conditions when soldering
chip EMI suppression filters.

SOLDERING CONDITIONS

Flow Solder		
	Pre-heating	Soldering
		Gradual cooling (in air)

12mm width plastic tape



Part Number	Cavity Size			Minimum QTY.	
	a	b	c	$\phi 180\text{mm}$	$\phi 330\text{mm}$
BLM41	4.8	1.9	1.75	2500	8000
NFM41R/4516R NFM4516P	4.8	1.8	1.1	4000	-
NFM61R/61RH	7.2	1.9	1.75	2500	8000
VFM41R	4.8	1.8	1.35	2500	-

Notice (storage and operating condition)

< CLEANING >

Following conditions should be observed when cleaning chip EMI filter.

1. Cleaning Temperature : 60degree C max. (40degree C max. for CFC alternatives and alcohol cleaning agents)
2. Ultrasonic
 - Output : 20W/liter max.
 - Duration : 5 minutes max.
 - Frequency : 28kHz to 40kHz
3. Cleaning agent

The following list of cleaning agents have been tested on the individual components. Evaluation of final assembly should be completed prior to production.

Do not clean PLM250, PLW3216S series. In case of cleaning, please contact Murata engineering.

 - a) CFC alternatives and alcohol cleaning agents
 - Isopropyl alcohol (IPA)
 - HCFC-225
 - b) Aqueous cleaning agent
 - Surface active agent (Clean Thru 750H)
 - Hydrocarbon (Techno Cleaner 335)
 - High grade alcohol (Pine Alpha ST-100S)*
 - *VFM41R, VCM11R/21R series cannot be cleaned with high grade alcohol type aqueous cleaning agent.
 - Alkaline saponifier (Aqua Cleaner 240 -cleaner should be diluted within 20% using deionized water.)
4. Ensure that flux residue is completely removed. Component should be thoroughly dried after aqueous agent has been removed with deionized water.
5. Some products may become slightly whitened. However, product performance or usage is not affected. For additional cleaning methods, please contact Murata engineering.

< OPERATING ENVIRONMENT >

Do not use products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

< STORAGE AND HANDLING REQUIREMENTS >

1. Storage Period

Products which inspected in Murata over 12 months ago should be examined and used, which can be confirmed with inspection No. marked on the container.

Solderability should be checked if this period is exceeded. (NFM41P/46P, VCM series should be used within 6 months.)
2. Storage conditions
 - a) Storage temperature : -10degree C to 40degree C
 - Relative humidity : 30% to 70%
 - Avoid sudden changes in temperature and humidity.
 - b) Do not store products in a chemical atmosphere such as chlorine gas, acid or sulfide gas.

CAUTION (rating)

Rated Current/Rated Voltage/Operating Temperature
Do not use products beyond the rated current, the
rated voltage and the operating temperature range,
or, a fire may result due to the deterioration of
the insulation resistance, excessive heat, etc.

CAUTION (soldering and mounting)

Mounting density

Give special attention when mounting products close to other product that radiate heat. The excessive heat by other products may cause deterioration of insulation resistance and excessive heat at this product, resulting in the fire.